

L Number	Hits	Search Text	DB	Time stamp
1	6088	((Chip or die or wafer) with Mirror)	USPAT	2003/10/05 13:43
2	802	((Chip or die or wafer) with Mirror) and (Wafer same (cut or saw or singulate))	USPAT	2003/10/05 15:53
3	694	((Chip or die or wafer) with Mirror) and (Wafer same (cut or saw or singulate)) and (@ad<20000510)	USPAT	2003/10/05 15:17
4	40	((Chip or die or wafer) with Mirror) and (Wafer same (cut or saw or singulate)) and (@ad<20000510) and ((photoresist or resist)with Mirror)	USPAT	2003/10/05 13:44
5	40	((Chip or die or wafer) with Mirror) and (Wafer same (cut or saw or singulate)) and (@ad<20000510) and ((photoresist or resist) with Mirror)	USPAT	2003/10/05 15:51
6	2	6063696.URPN.	USPAT	2003/10/05 14:08
7	2	6063696.URPN.	USPAT	2003/10/05 14:26
8	12	("5107328" "5435876" "5516728" "5605489" "5766367" "5872046" "5923995" "5951813" "5958510" "5963788" "6025767" "6063696").PN.	USPAT	2003/10/05 14:28
9	14	((Chip or die or wafer) with Mirror) and (Wafer same (cut or saw or singulate)) and ((photoresist or resist or protective) with (Mirror and (remove or removal)))	USPAT	2003/10/05 15:06
10	3	438/465.ccls. and ((photoresist or resist or protective) with (Mirror and (remove or removal)))	USPAT	2003/10/05 15:11
11	5	438/465.ccls. and ((photoresist or resist or protective) with (Mirror))	USPAT	2003/10/05 15:08
12	0	438/114.ccls. and ((photoresist or resist or protective) with (Mirror))	USPAT	2003/10/05 15:08
13	3	438/460.ccls. and ((photoresist or resist or protective) with (Mirror))	USPAT	2003/10/05 15:09
14	24	((photoresist or resist or protective) with (Mirror and (wire or wirebond)))	USPAT	2003/10/05 15:09
15	2	((photoresist or resist or protective) with (Mirror and (wire or wirebond))) and (Wafer same (cut or saw or singulate))	USPAT	2003/10/05 15:09
16	20	((photoresist or resist or protective) with (Mirror and (wire or wirebond))) and (@ad<20000510)	USPAT	2003/10/05 15:10
17	1	257/414.ccls. and ((photoresist or resist or protective) with (Mirror and (remove or removal)))	USPAT	2003/10/05 15:12
18	34	257/8.ccls. and ((photoresist or resist or protective) with (Mirror and (remove or removal)))	USPAT	2003/10/05 15:12
19	25	(257/8.ccls. and ((photoresist or resist or protective) with (Mirror and (remove or removal))) and (@ad<20000510)	USPAT	2003/10/05 15:42
20	1	("20010041381").PN.	US-PGPUB	2003/10/05 15:45
21	0	antisitckking with photoresist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/05 15:46
22	1	antisticking with photoresist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/05 15:46

23	5	antisticking same (photoresist or resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/05 15:48
24	5	((antisticking or antistck) same (photoresist or resist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/05 15:49
25	0	((antisticking or antistck) same (photoresist or resist)) not (antisticking same (photoresist or resist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/05 15:50
26	0	("6507082").PN.	US-PGPUB	2003/10/05 15:50
27	1	("6507082").PN.	USPAT	2003/10/05 15:50
28	0	6507082.URPN.	USPAT	2003/10/05 15:51
29	0	6507082.URPN.	USPAT	2003/10/05 15:51
30	0	6507082.URPN.	USPAT	2003/10/05 15:51
31	116	(wire or wirebond) and ((photoresist or resist) with Mirror)	USPAT	2003/10/05 15:52
32	26	((wire or wirebond) and ((photoresist or resist) with Mirror)) and (Wafer same (cut or saw or singulate))	USPAT	2003/10/05 15:53